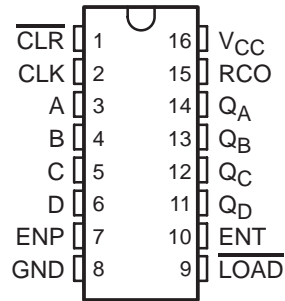


SN54HC163, SN74HC163 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS298D – JANUARY 1996 – REVISED – OCTOBER 2003

- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80- μ A Max I_{CC}
- Typical $t_{pd} = 14$ ns
- ± 4 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max
- Internal Look-Ahead for Fast Counting
- Carry Output for n-Bit Cascading
- Synchronous Counting
- Synchronously Programmable

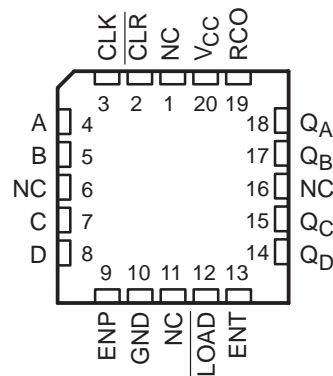
SN54HC163 . . . J OR W PACKAGE
SN74HC163 . . . D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)



description/ordering information

These synchronous, presettable counters feature an internal carry look-ahead for application in high-speed counting designs. The 'HC163 devices are 4-bit binary counters. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes normally associated with synchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

SN54HC163 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

| T _A | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|------------|--------------|-----------------------|------------------|
| -40°C to 85°C | PDIP – N | Tube of 25 | SN74HC163N | SN74HC163N |
| | SOIC – D | Tube of 40 | SN74HC163D | HC163 |
| | | Reel of 2500 | SN74HC163DR | |
| | | Reel of 250 | SN74HC163DT | |
| | SOP – NS | Reel of 2000 | SN74HC163NSR | HC163 |
| | SSOP – DB | Reel of 2000 | SN74HC163DBR | HC163 |
| -55°C to 125°C | TSSOP – PW | Tube of 90 | SN74HC163PW | HC163 |
| | | Reel of 2000 | SN74HC163PWR | |
| | | Reel of 250 | SN74HC163PWT | |
| -55°C to 125°C | CDIP – J | Tube of 25 | SNJ54HC163J | SNJ54HC163J |
| | CFP – W | Tube of 150 | SNJ54HC163W | SNJ54HC163W |
| | LCCC – FK | Tube of 55 | SNJ54HC163FK | SNJ54HC163FK |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54HC163, SN74HC163

4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS298D – JANUARY 1996 – REVISED – OCTOBER 2003

description/ordering information (continued)

These counters are fully programmable; that is, they can be preset to any number between 0 and 9 or 15. As presetting is synchronous, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

The clear function for the 'HC163 devices is synchronous. A low level at the clear ($\overline{\text{CLR}}$) input sets all four of the flip-flop outputs low after the next low-to-high transition of CLK, regardless of the levels of the enable inputs. This synchronous clear allows the count length to be modified easily by decoding the Q outputs for the maximum count desired. The active-low output of the gate used for decoding is connected to $\overline{\text{CLR}}$ to synchronously clear the counter to 0000 (LLLL).

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. ENP, ENT, and a ripple-carry output (RCO) are instrumental in accomplishing this function. Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. Enabling RCO produces a high-level pulse while the count is maximum (9 or 15 with Q_A high). This high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

These counters feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or $\overline{\text{LOAD}}$) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.

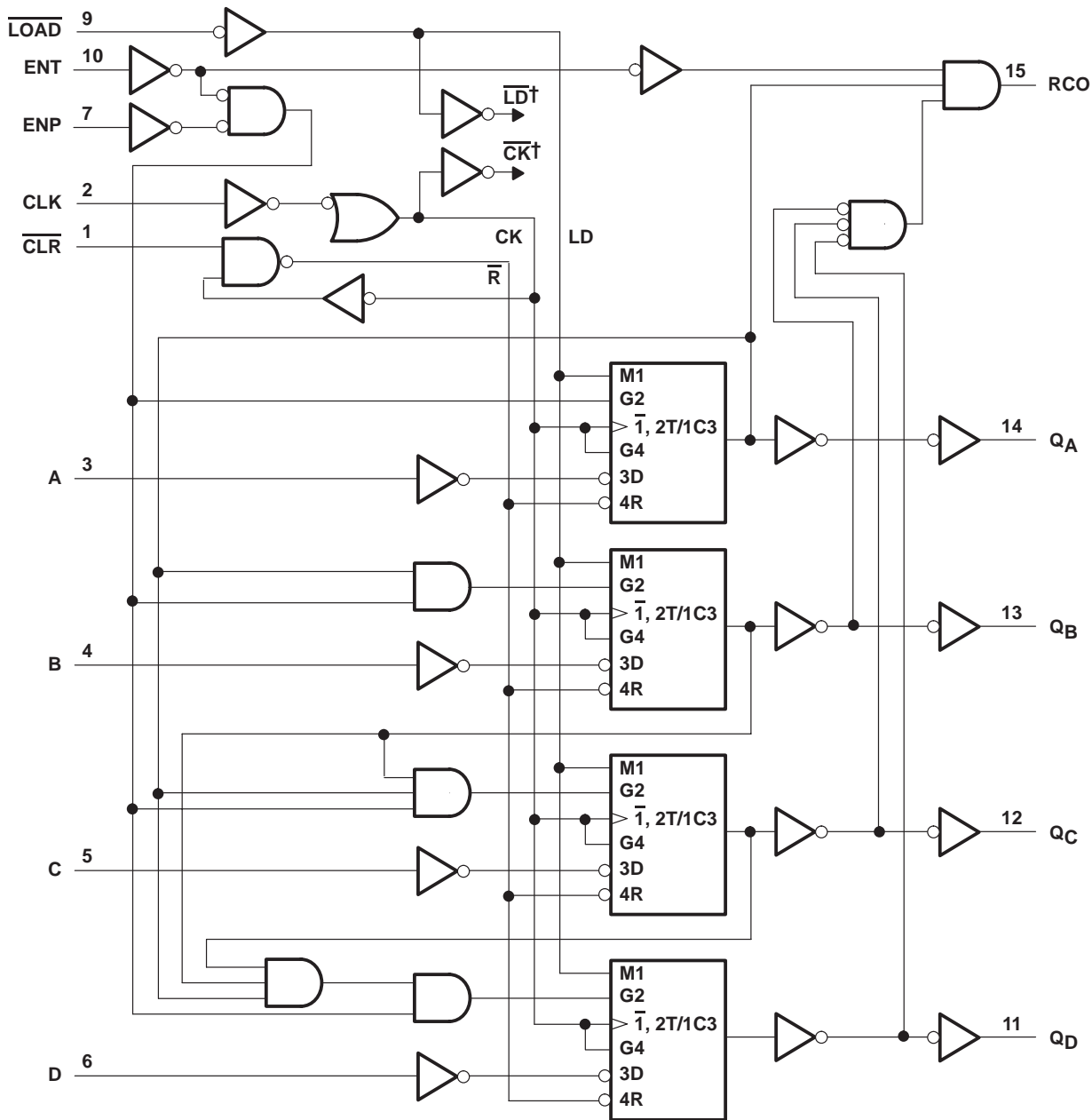


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SN54HC163, SN74HC163 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS298D – JANUARY 1996 – REVISED – OCTOBER 2003

logic diagram (positive logic)



† For simplicity, routing of complementary signals \bar{LD} and \bar{CK} is not shown on this overall logic diagram. The uses of these signals are shown on the logic diagram of the D/T flip-flops.

Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

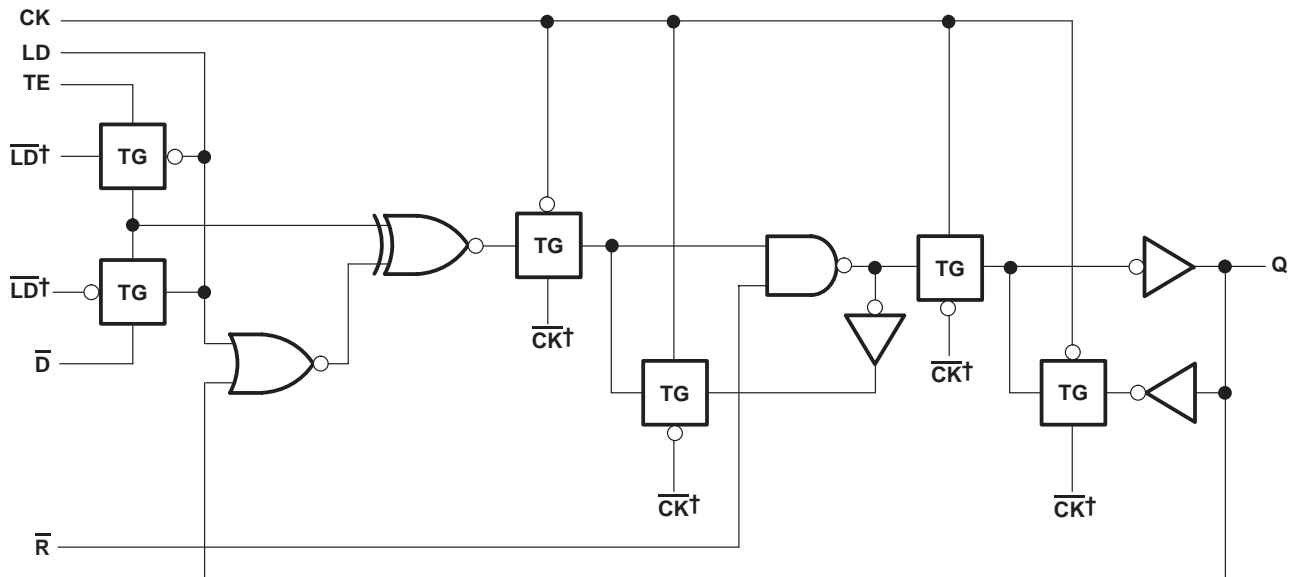
SN54HC163, SN74HC163 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS298D – JANUARY 1996 – REVISED – OCTOBER 2003

logic symbol, each D/T flip-flop



logic diagram, each D/T flip-flop (positive logic)

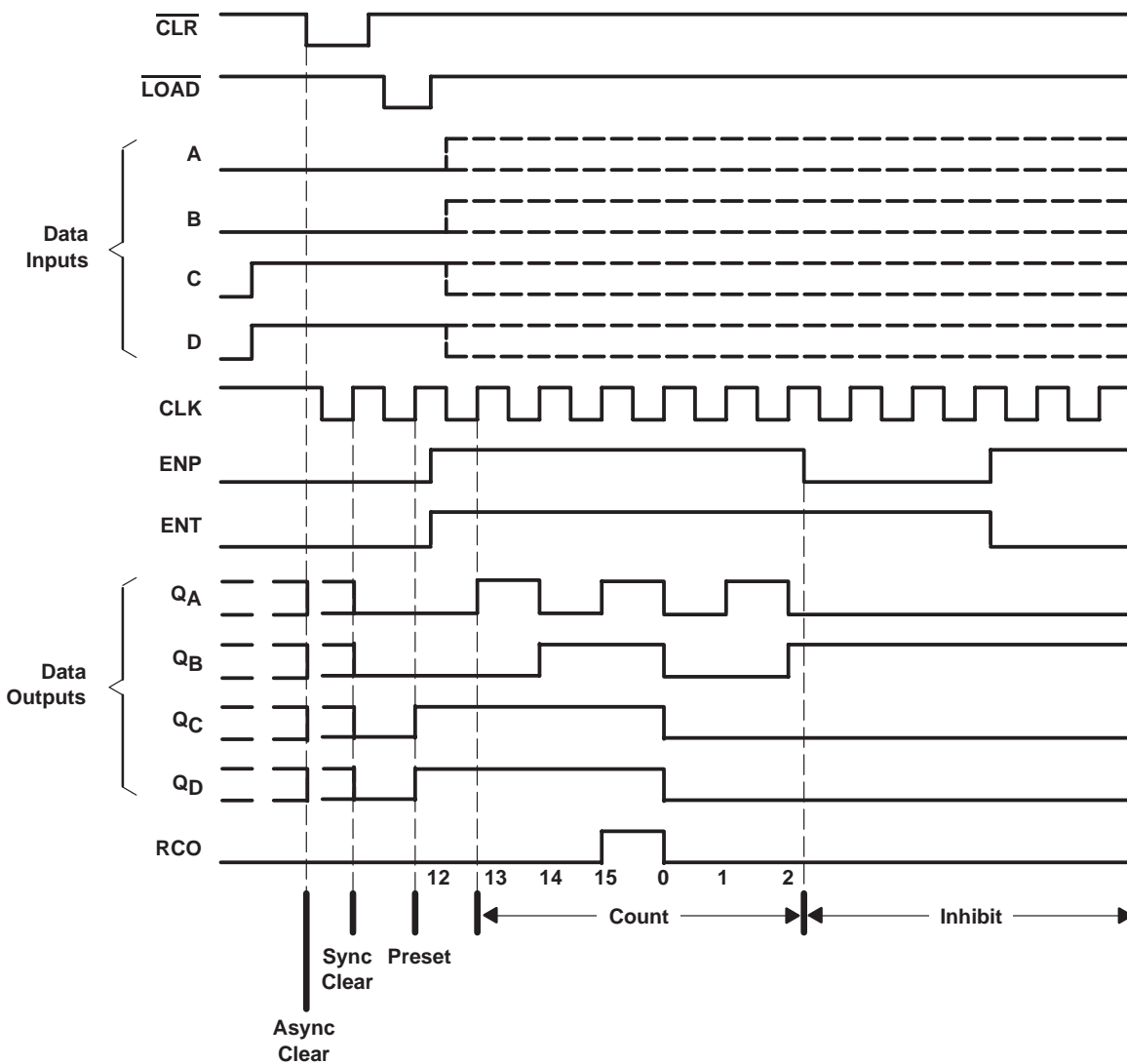


† The origins of \overline{LD} and \overline{CK} are shown in the logic diagram of the overall device.

typical clear, preset, count, and inhibit sequence

The following sequence is illustrated below:

1. Clear outputs to zero (synchronous)
2. Preset to binary 12
3. Count to 13, 14, 15, 0, 1, and 2
4. Inhibit



SN54HC163, SN74HC163

4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS298D – JANUARY 1996 – REVISED – OCTOBER 2003

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|---|----------------|
| Supply voltage range, V_{CC} | –0.5 V to 7 V |
| Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1) | ±20 mA |
| Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1) | ±20 mA |
| Continuous output current, I_O ($V_O = 0$ to V_{CC}) | ±25 mA |
| Continuous current through V_{CC} or GND | ±50 mA |
| Package thermal impedance, θ_{JA} (see Note 2): D package | 73°C/W |
| DB package | 82°C/W |
| N package | 67°C/W |
| NS package | 64°C/W |
| PW package | 108°C/W |
| Storage temperature range, T_{stg} | –65°C to 150°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

| | | SN54HC163 | | | SN74HC163 | | | UNIT |
|-----------------------|---------------------------------|------------------|-----|----------|-----------|-----|----------|------|
| | | MIN | NOM | MAX | MIN | NOM | MAX | |
| V_{CC} | Supply voltage | 2 | 5 | 6 | 2 | 5 | 6 | V |
| V_{IH} | High-level input voltage | $V_{CC} = 2$ V | | 1.5 | 1.5 | | V | |
| | | $V_{CC} = 4.5$ V | | 3.15 | 3.15 | | | |
| | | $V_{CC} = 6$ V | | 4.2 | 4.2 | | | |
| V_{IL} | Low-level input voltage | $V_{CC} = 2$ V | | | 0.5 | | V | |
| | | $V_{CC} = 4.5$ V | | | 1.35 | | | |
| | | $V_{CC} = 6$ V | | | 1.8 | | | |
| V_I | Input voltage | 0 | | V_{CC} | 0 | | V_{CC} | V |
| V_O | Output voltage | 0 | | V_{CC} | 0 | | V_{CC} | V |
| $\Delta t/\Delta v$ ‡ | Input transition rise/fall time | $V_{CC} = 2$ V | | | 1000 | | ns | |
| | | $V_{CC} = 4.5$ V | | | 500 | | | |
| | | $V_{CC} = 6$ V | | | 400 | | | |
| T_A | Operating free-air temperature | –55 | | 125 | –40 | | 85 | °C |

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

‡ If this device is used in the threshold region (from $V_{ILmax} = 0.5$ V to $V_{IHmin} = 1.5$ V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at $t_t = 1000$ ns and $V_{CC} = 2$ V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.



SN54HC163, SN74HC163 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS298D – JANUARY 1996 – REVISED – OCTOBER 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | V _{CC} | T _A = 25°C | | | SN54HC163 | | SN74HC163 | | UNIT | |
|-----------------|---|---------------------------|-----------------|-----------------------|-------|------|-----------|-------|-----------|-------|------|----|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | | |
| V _{OH} | V _I = V _{IH} or V _{IL} | I _{OH} = -20 μA | 2 V | 1.9 | 1.998 | | 1.9 | | 1.9 | V | | |
| | | | 4.5 V | 4.4 | 4.499 | | 4.4 | | 4.4 | | | |
| | | | 6 V | 5.9 | 5.999 | | 5.9 | | 5.9 | | | |
| | | I _{OH} = -4 mA | 4.5 V | 3.98 | 4.3 | | 3.7 | | 3.84 | | | |
| | | I _{OH} = -5.2 mA | 6 V | 5.48 | 5.8 | | 5.2 | | 5.34 | | | |
| V _{OL} | V _I = V _{IH} or V _{IL} | I _{OL} = 20 μA | 2 V | | 0.002 | 0.1 | | 0.1 | | 0.1 | V | |
| | | | 4.5 V | | 0.001 | 0.1 | | 0.1 | | 0.1 | | |
| | | | 6 V | | 0.001 | 0.1 | | 0.1 | | 0.1 | | |
| | | I _{OL} = 4 mA | 4.5 V | | 0.17 | 0.26 | | 0.4 | | 0.33 | | |
| | | I _{OL} = 5.2 mA | 6 V | | 0.15 | 0.26 | | 0.4 | | 0.33 | | |
| I _I | V _I = V _{CC} or 0 | | 6 V | | ±0.1 | ±100 | | ±1000 | | ±1000 | nA | |
| I _{CC} | V _I = V _{CC} or 0, I _O = 0 | | 6 V | | | | 8 | | 160 | | 80 | μA |
| C _i | | | 2 V to 6 V | | 3 | 10 | | | 10 | | 10 | pF |

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

| | | | V _{CC} | T _A = 25°C | | SN54HC163 | | SN74HC163 | | UNIT |
|--------------------|--|-----------------|-----------------|-----------------------|-----|-----------|-----|-----------|-----|------|
| | | | | MIN | MAX | MIN | MAX | MIN | MAX | |
| f _{clock} | Clock frequency | | 2 V | | 6 | | 4.2 | | 5 | MHz |
| | | | 4.5 V | | 31 | | 21 | | 25 | |
| | | | 6 V | | 36 | | 25 | | 29 | |
| t _w | Pulse duration | CLK high or low | 2 V | 80 | | 120 | | 100 | | ns |
| | | | 4.5 V | 16 | | 24 | | 20 | | |
| | | | 6 V | 14 | | 20 | | 17 | | |
| t _{su} | Setup time before CLK↑ | A, B, C, or D | 2 V | 150 | | 225 | | 190 | | ns |
| | | | 4.5 V | 30 | | 45 | | 38 | | |
| | | | 6 V | 26 | | 38 | | 32 | | |
| | | LOAD low | 2 V | 135 | | 205 | | 170 | | |
| | | | 4.5 V | 27 | | 41 | | 34 | | |
| | | | 6 V | 23 | | 35 | | 29 | | |
| | | ENP, ENT | 2 V | 170 | | 255 | | 215 | | |
| | | | 4.5 V | 34 | | 51 | | 43 | | |
| | | | 6 V | 29 | | 43 | | 37 | | |
| | | CLR low | 2 V | 160 | | 240 | | 200 | | |
| | | | 4.5 V | 32 | | 48 | | 40 | | |
| | | | 6 V | 27 | | 41 | | 34 | | |
| | | CLR inactive | 2 V | 160 | | 240 | | 200 | | |
| | | | 4.5 V | 32 | | 48 | | 40 | | |
| | | | 6 V | 27 | | 41 | | 34 | | |
| t _h | Hold time, all synchronous inputs after CLK↑ | | 2 V | 0 | | 0 | | 0 | ns | |
| | | | 4.5 V | 0 | | 0 | | 0 | | |
| | | | 6 V | 0 | | 0 | | 0 | | |



SN54HC163, SN74HC163

4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS298D – JANUARY 1996 – REVISED – OCTOBER 2003

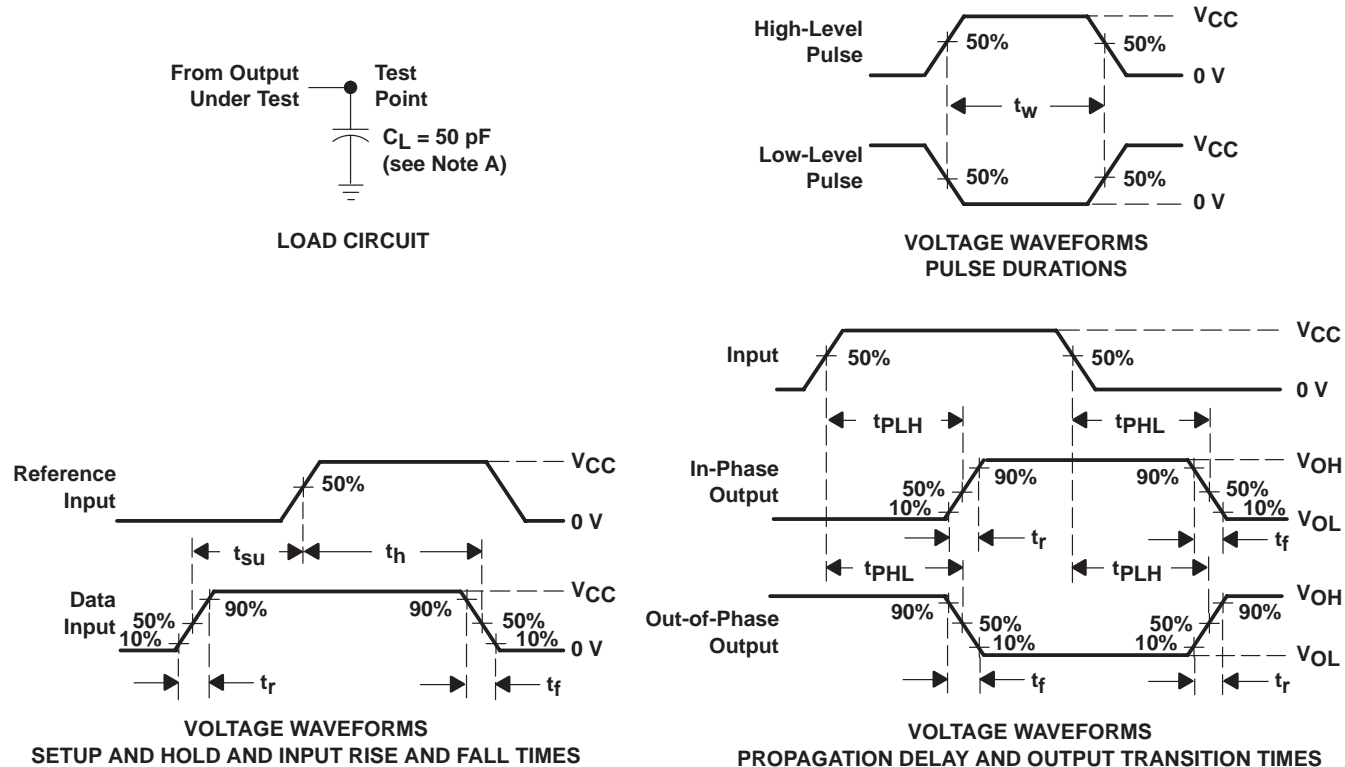
switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V_{CC} | $T_A = 25^\circ\text{C}$ | | | SN54HC163 | | SN74HC163 | | UNIT |
|-----------|--------------|-------------|----------|--------------------------|-----|-----|-----------|-----|-----------|-----|------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| f_{max} | | | 2 V | 6 | 14 | | 4.2 | | 5 | MHz | |
| | | | 4.5 V | 31 | 40 | | 21 | | 25 | | |
| | | | 6 V | 36 | 44 | | 25 | | 29 | | |
| t_{pd} | CLK | RCO | 2 V | | 83 | 215 | | 325 | | 270 | ns |
| | | | 4.5 V | | 24 | 43 | | 65 | | 54 | |
| | | | 6 V | | 20 | 37 | | 55 | | 46 | |
| | | Any Q | 2 V | | 80 | 205 | | 310 | | 255 | |
| | | | 4.5 V | | 25 | 41 | | 62 | | 51 | |
| | | | 6 V | | 21 | 35 | | 53 | | 43 | |
| | ENT | RCO | 2 V | | 62 | 195 | | 295 | | 245 | |
| | | | 4.5 V | | 17 | 39 | | 59 | | 49 | |
| | | | 6 V | | 14 | 33 | | 50 | | 42 | |
| t_t | | Any | 2 V | | 38 | 75 | | 110 | | 95 | ns |
| | | | 4.5 V | | 8 | 15 | | 22 | | 19 | |
| | | | 6 V | | 6 | 13 | | 19 | | 16 | |

operating characteristics, $T_A = 25^\circ\text{C}$

| PARAMETER | TEST CONDITIONS | TYP | UNIT |
|--|-----------------|-----|------|
| C_{pd} Power dissipation capacitance | No load | 60 | pF |

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and test-fixture capacitance.
 - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 6 \text{ ns}$, $t_f = 6 \text{ ns}$.
 - C. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN54HC163, SN74HC163 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS298D – JANUARY 1996 – REVISED – OCTOBER 2003

APPLICATION INFORMATION

n-bit synchronous counters

This application demonstrates how the look-ahead carry circuit can be used to implement a high-speed n-bit counter. The 'HC163 devices count in binary. Virtually any count mode (modulo-N, N_1 -to- N_2 , N_1 -to-maximum) can be used with this fast look-ahead circuit.

The application circuit shown in Figure 2 is not valid for clock frequencies above 18 MHz (at 25°C and 4.5-V V_{CC}). The reason for this is that there is a glitch that is produced on the second stage's RCO and every succeeding stage's RCO. This glitch is common to all HC vendors that Texas Instruments has evaluated, in addition to the bipolar equivalents (LS, ALS, AS).



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SN54HC163, SN74HC163 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS298D – JANUARY 1996 – REVISED – OCTOBER 2003

APPLICATION INFORMATION

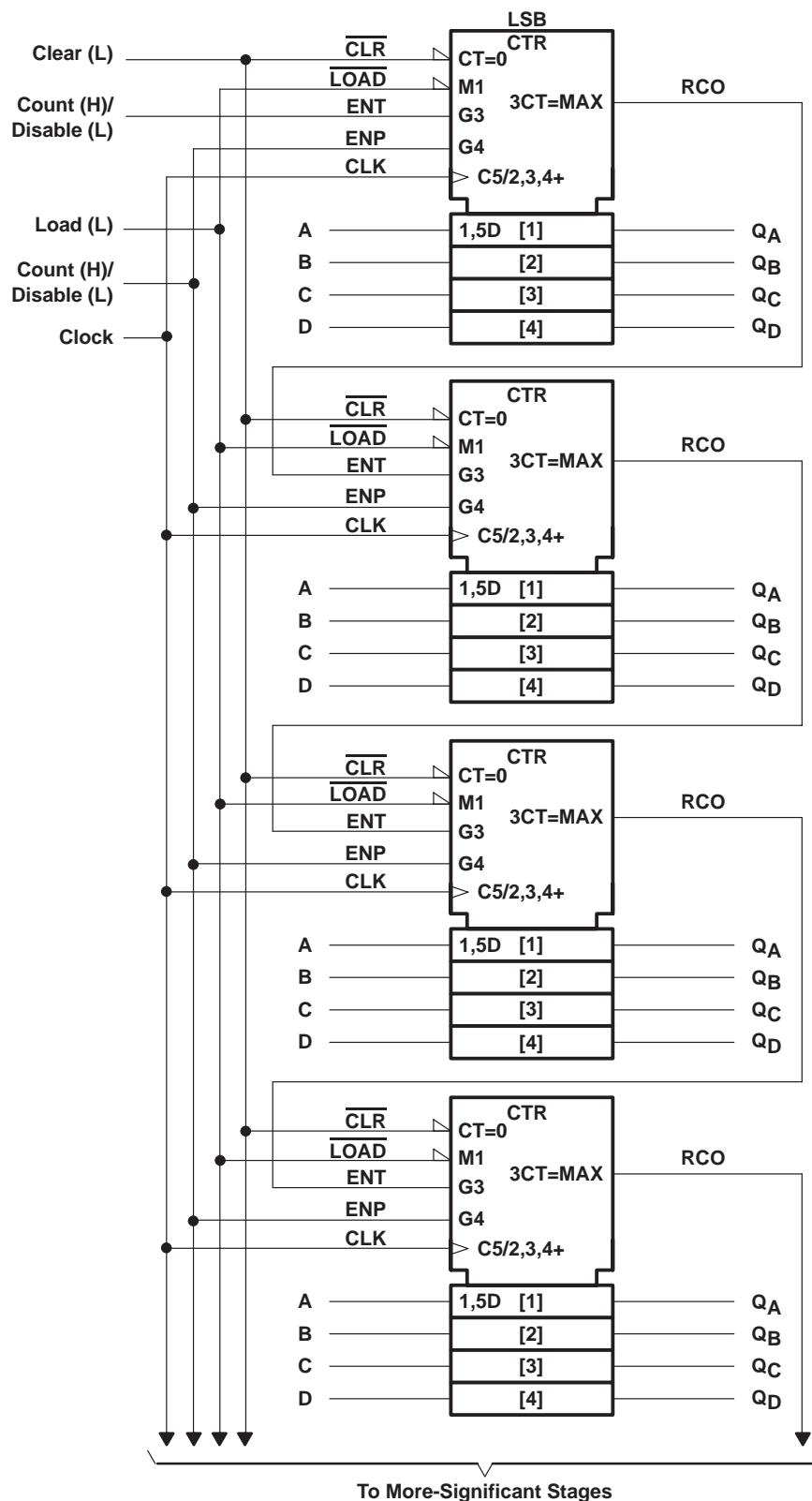


Figure 2



SN54HC163, SN74HC163 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS298D – JANUARY 1996 – REVISED – OCTOBER 2003

APPLICATION INFORMATION

n-bit synchronous counters (continued)

The glitch on RCO is caused because the propagation delay of the rising edge of Q_A of the second stage is shorter than the propagation delay of the falling edge of ENT. RCO is the product of ENT, Q_A , Q_B , Q_C , and Q_D ($ENT \times Q_A \times Q_B \times Q_C \times Q_D$). The resulting glitch is about 7–12 ns in duration. Figure 3 shows the condition in which the glitch occurs. For simplicity, only two stages are being considered, but the results can be applied to other stages. Q_B , Q_C , and Q_D of the first and second stage are at logic one, and Q_A of both stages are at logic zero (1110 1110) after the first clock pulse. On the rising edge of the second clock pulse, Q_A and RCO of the first stage go high. On the rising edge of the third clock pulse, Q_A and RCO of the first stage return to a low level, and Q_A of the second stage goes to a high level. At this time, the glitch on RCO of the second stage appears because of the race condition inside the chip.

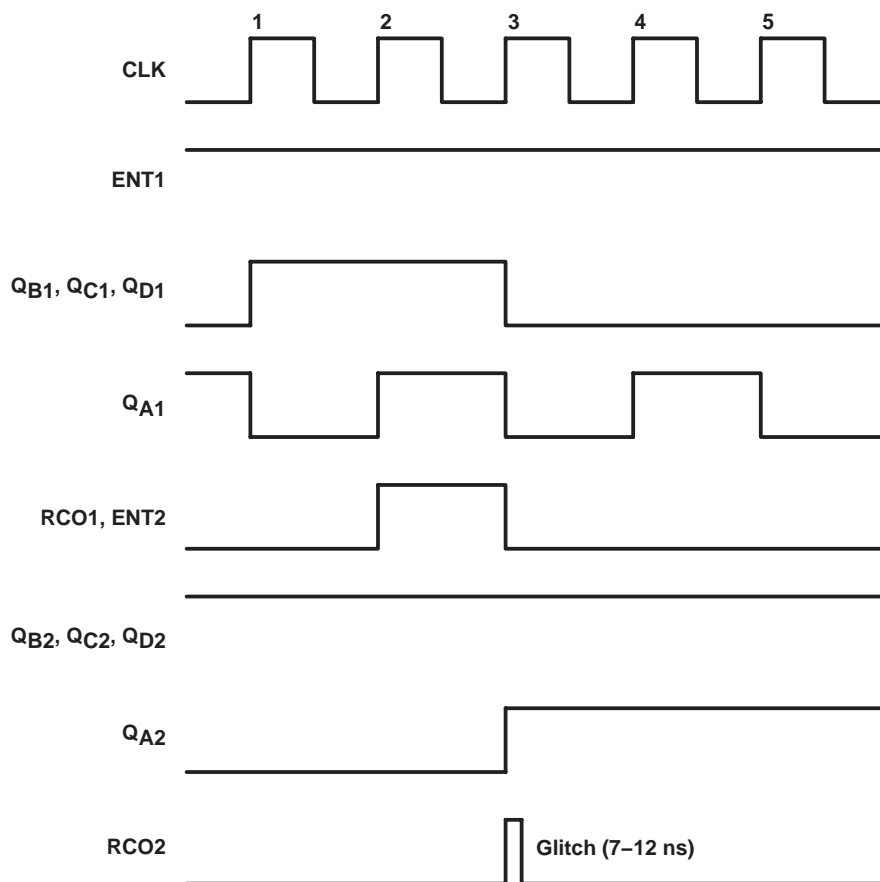


Figure 3

The glitch causes a problem in the next stage (stage three) if the glitch is still present when the next rising clock edge appears (clock pulse 4). To ensure that this does not happen, the clock frequency must be less than the inverse of the sum of the clock-to-RCO propagation delay and the glitch duration (t_g). In other words, $f_{max} = 1/(t_{pd} \text{ CLK-to-RCO} + t_g)$. For example, at 25°C at 4.5-V V_{CC} , the clock-to-RCO propagation delay is 43 ns and the maximum duration of the glitch is 12 ns. Therefore, the maximum clock frequency that the cascaded counters can use is 18 MHz. The following tables contain the f_{clock} , t_w , and f_{max} specifications for applications that use more than two 'HC163 devices cascaded together.

SN54HC163, SN74HC163 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS298D – JANUARY 1996 – REVISED – OCTOBER 2003

APPLICATION INFORMATION

n-bit synchronous counters (continued)

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

| | V _{CC} | T _A = 25°C | | SN54HC163 | | SN74HC163 | | UNIT |
|--|-----------------|-----------------------|-----|-----------|-----|-----------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| f _{clock} Clock frequency | 2 V | | 3.6 | | 2.5 | | 2.9 | MHz |
| | 4.5 V | | 18 | | 12 | | 14 | |
| | 6 V | | 21 | | 14 | | 17 | |
| t _w Pulse duration, CLK high or low | 2 V | 140 | | 200 | | 170 | | ns |
| | 4.5 V | 28 | | 40 | | 36 | | |
| | 6 V | 24 | | 36 | | 30 | | |

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Note 4)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} | T _A = 25°C | | SN54HC163 | | SN74HC163 | | UNIT |
|------------------|--------------|-------------|-----------------|-----------------------|-----|-----------|-----|-----------|-----|------|
| | | | | MIN | MAX | MIN | MAX | MIN | MAX | |
| f _{max} | | | 2 V | 3.6 | | 2.5 | | 2.9 | | MHz |
| | | | 4.5 V | 18 | | 12 | | 14 | | |
| | | | 6 V | 21 | | 14 | | 17 | | |

NOTE 4: These limits apply only to applications that use more than two 'HC163 devices cascaded together.

If the 'HC163 devices are used as a single unit, or only two cascaded together, then the maximum clock frequency that the devices can use is not limited because of the glitch. In these situations, the devices can be operated at the maximum specifications.

A glitch can appear on RCO of a single 'HC163 device, depending on the relationship of ENT to CLK. Any application that uses RCO to drive any input, except an ENT of another cascaded 'HC163 device, must take this into consideration.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------------|-------------------------|
| 86076012A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 86076012A SNJ54HC 163FK | Samples |
| 8607601EA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 8607601EA SNJ54HC163J | Samples |
| JM38510/66304BEA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 66304BEA | Samples |
| M38510/66304BEA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 66304BEA | Samples |
| SN54HC163J | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | SN54HC163J | Samples |
| SN74HC163D | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HC163 | Samples |
| SN74HC163DG4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HC163 | Samples |
| SN74HC163DR | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HC163 | Samples |
| SN74HC163DRE4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HC163 | Samples |
| SN74HC163DT | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HC163 | Samples |
| SN74HC163N | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | SN74HC163N | Samples |
| SN74HC163NE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | SN74HC163N | Samples |
| SN74HC163NSR | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HC163 | Samples |
| SN74HC163PW | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HC163 | Samples |
| SN74HC163PWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HC163 | Samples |
| SN74HC163PWT | ACTIVE | TSSOP | PW | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HC163 | Samples |
| SNJ54HC163FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 86076012A SNJ54HC | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|-------------------------|----------------------|--------------|--------------------------|----------------|
| | | | | | | | | | | 163FK | |
| SNJ54HC163J | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 8607601EA SNJ54HC163J | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HC163, SN74HC163 :

- Catalog: [SN74HC163](#)
- Automotive: [SN74HC163-Q1](#), [SN74HC163-Q1](#)
- Military: [SN54HC163](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74HC163DR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74HC163NSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74HC163PWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74HC163PWT | TSSOP | PW | 16 | 250 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74HC163DR | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |
| SN74HC163NSR | SO | NS | 16 | 2000 | 367.0 | 367.0 | 38.0 |
| SN74HC163PWR | TSSOP | PW | 16 | 2000 | 367.0 | 367.0 | 35.0 |
| SN74HC163PWT | TSSOP | PW | 16 | 250 | 367.0 | 367.0 | 35.0 |

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



| NO. OF TERMINALS ** | A | | B | |
|---------------------|------------------|------------------|------------------|------------------|
| | MIN | MAX | MIN | MAX |
| 20 | 0.342 (8,69) | 0.358 (9,09) | 0.307 (7,80) | 0.358 (9,09) |
| 28 | 0.442 (11,23) | 0.458 (11,63) | 0.406 (10,31) | 0.458 (11,63) |
| 44 | 0.640 (16,26) | 0.660 (16,76) | 0.495 (12,58) | 0.560 (14,22) |
| 52 | 0.740 (18,78) | 0.761 (19,32) | 0.495 (12,58) | 0.560 (14,22) |
| 68 | 0.938 (23,83) | 0.962 (24,43) | 0.850 (21,6) | 0.858 (21,8) |
| 84 | 1.141 (28,99) | 1.165 (29,59) | 1.047 (26,6) | 1.063 (27,0) |



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN





- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

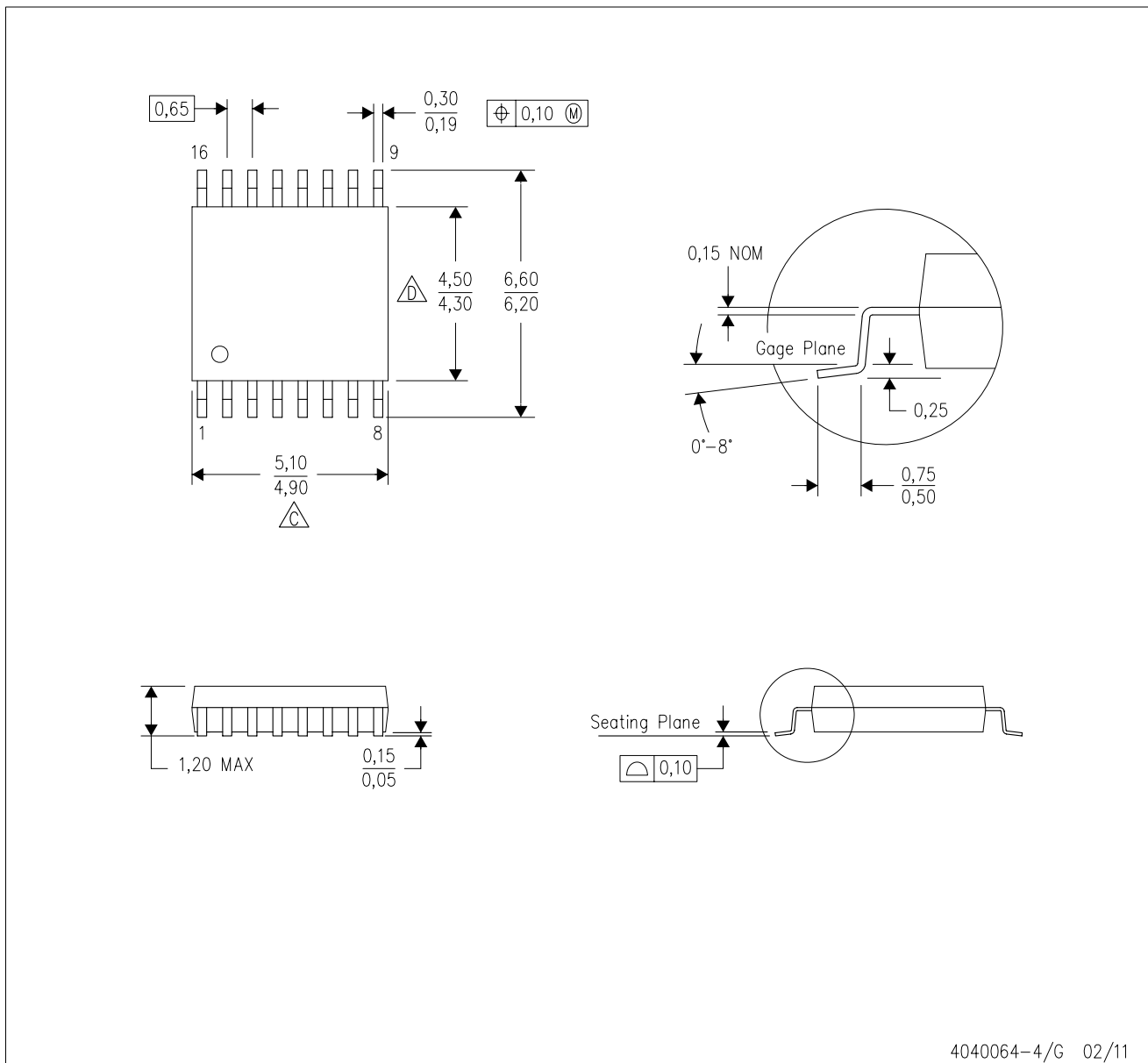


4211283-4/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE

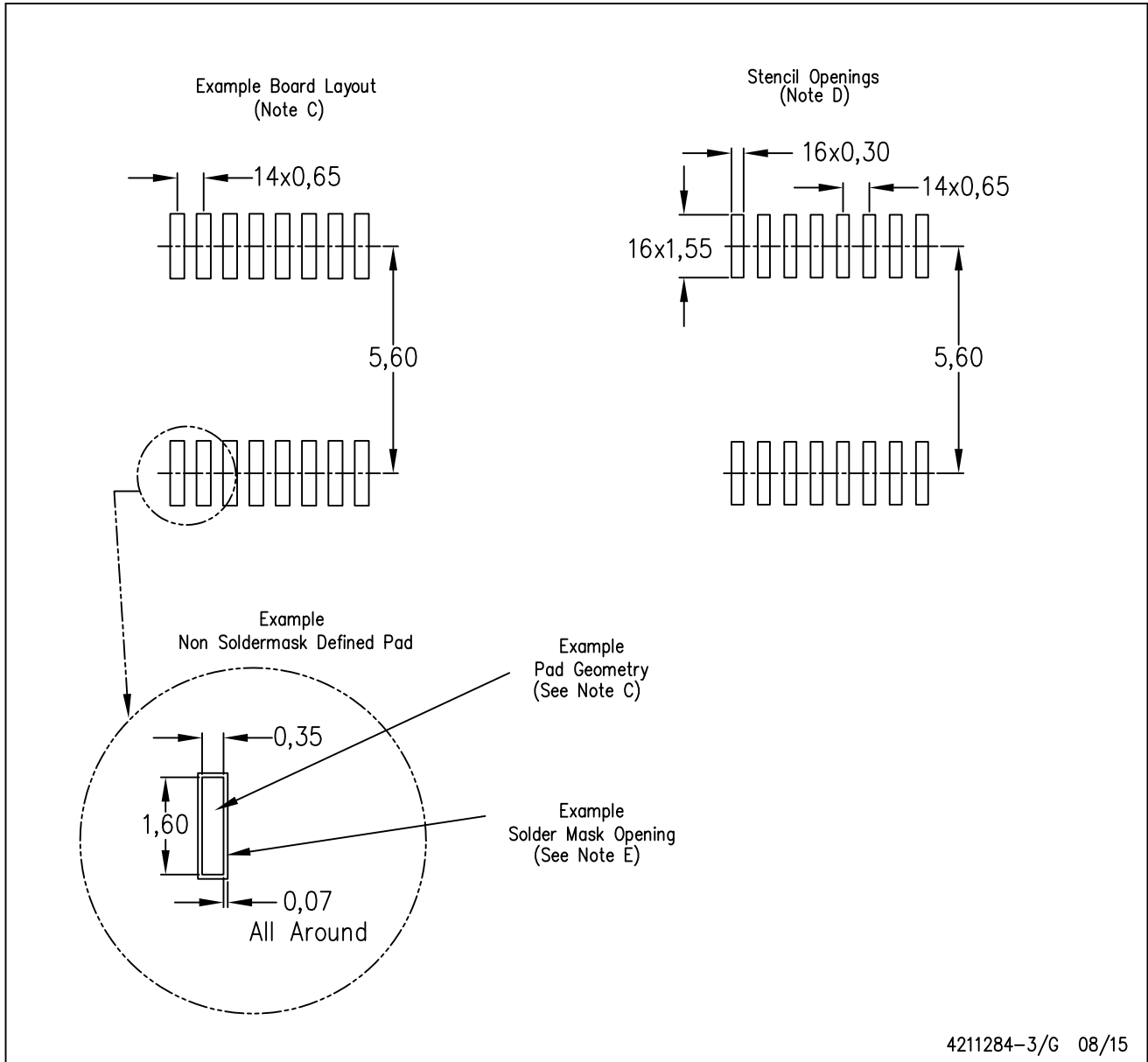


4040064-4/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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